MATERIAL DECLARATION SHEET

BOURNS®

Material Number	CRM1206 Series (over 1Ω)		
Product Line	High power chip resistors		
Compliance Date	**09/01/2016**		
RoHS Compliant	**Yes**	MSL	**N/A**

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic	Substrate	8.588	Aluminum oxide	1344-28-1	96	81.946	85.36
				Silicon dioxide	14808-60-7	2	1.707	
				Magnesium oxide	1309-48-4	2	1.707	
2	Top conductor	Silver	0.162	Silver	7440-22-4	100	1.61	1.61
3	Bottom conductor	Silver	0.0543	Silver	7440-22-4	100	0.54	0.54
4	Resistor	Ruthenium Oxide	0.1087	Silver	7440-22-4	40	0.432	1.08
				Ruthenium(IV) oxide	12036-10-1	20	0.216	
				Palladium	7440-05-3	15	0.162	
				Glass	65997-17-3	14.9	0.161	
				Lead In Glass	7439-92-1	10.1	0.109	
5	First encapsulating	Glass	0.1038	Glass	65997-17-3	92	0.949	1.032
				Chromium(III) oxide	1308-38-9	8	0.083	
6	Overcoat	Resin	0.2327	Resin	25036-25-3	100	2.313	2.313
7	Side conductor	Silver	0.2341	Silver	7440-22-4	85	1.978	2.327
				Resin	9003-36-5	15	0.349	
8	Plating (Middle)	Nickel	0.1985	Nickel	7440-02-0	100	1.973	1.973
9	Plating (Outer)	Tin	0.3573	Tin	7440-31-5	100	3.551	3.551
10	Marking	Resin	0.0215	Resin	29690-82-2	70	0.15	0.214
				Titanium oxide	1317-80-2	30	0.064	
		Total weight	10.0609					

This Document was updated on: 12/24/2019

Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption: 7(c)-1 Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in

Capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.